

AMENDMENTS TO THE CLAIMS

This listing of the claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A method for surface treatment of a gold-plated body, wherein ~~the~~ a surface of the gold-plated body obtained by using electrically conductive substrates having a Ni layer on the periphery of electrically conductive materials composed of Co-Ni-Fe alloy, is subjected to an annealing treatment at a temperature of 350 to 790°C so that a large number of sulfur-containing molecules can be immobilized thereon.
2. (Original) The method for surface treatment of a gold-plated body, according to claim 1, wherein the treatment is conducted so as to obtain a structure in which the surface gold crystals have no less than 30% planes with (1, 1, 1) orientation.
3. (Original) The method for surface treatment of a gold-plated body, according to claim 1 or claim 2, wherein said gold-plated body is an electroplated body obtained by immersing an electrically conductive substrate in a gold plating solution and passing an electric current through said electrically conductive substrate and said gold plating solution.
4. (Original) The method for surface treatment of a gold-plated body, according to claim 3, wherein a crystal growth enhancer is added to said gold plating solution.

5. (Original) The method for surface treatment of a gold-plated body, according to either claim 1 or claim 2, wherein said sulfur-containing molecule comprises a nucleic acid residue, a protein residue, or a protein-bondable group.

6. (Original) The method for surface treatment of a gold-plated body, according to claim 1 or claim 2, wherein said sulfur-containing molecule is a probe for detecting a gene with an unconfirmed base sequence.

7. (Canceled)

8. (Canceled)

9. (Currently amended) A method for the immobilization of sulfur-containing molecules, wherein a large number of sulfur-containing molecules are immobilized on ~~the~~ a surface-treated product of a gold-plated body, wherein the surface-treated product is obtained by conducting a surface treatment by the surface treatment method according to claim 1 or claim 2 comprising subjecting a surface of the gold-plated body to an annealing treatment at a temperature of 350 to 790°C.

10. (Currently amended) A method for the manufacture of a gold-plated body, obtained by using electrically conductive substrates having a Ni layer on the periphery of electrically conductive materials composed of Co-Ni-Fe alloy, that allows a large number of

sulfur-containing molecules to be immobilized on the surface thereof, wherein surface gold crystals are formed from a starting material comprising a crystal growth enhancer.

11. (Original) The method for the manufacture of a gold-plated body, according to claim 10, wherein the gold-plated body is obtained by adding a crystal growth enhancer to a gold plating solution, immersing an electrically conductive substrate therein, and passing an electric current through said electrically conductive substrate and said gold plating solution having the crystal growth enhancer added thereto.

12. (Original) The method for the manufacture of a gold-plated body, according to claim 10 or claim 11, wherein the formation of the surface gold crystals is conducted so as to obtain a structure in which the surface gold crystals have no less than 30% planes with (1, 1, 1) orientation.

13. (Original) The method for the manufacture of a gold-plated body, according to claim 10 or claim 11, wherein said sulfur-containing molecule comprises a nucleic acid residue, a protein residue, or a protein-bondable group.

14. (Original) The method for the manufacture of a gold-plated body, according to claim 10 or claim 11, wherein said sulfur-containing molecule is a probe for detecting a gene with an unconfirmed base sequence.

15. (Canceled)

16. (Canceled)

17. (Currently amended) A method for the immobilization of sulfur-containing molecules, wherein a large number of sulfur-containing molecules are immobilized on ~~the~~ a gold-plated body, wherein the gold-plated body is obtained by the a manufacturing method according to claim 10 or claim 11 comprising forming surface gold crystals from a starting material comprising a crystal growth enhancer.

18. (New) The method of claim 9, wherein the surface treatment is conducted so as to obtain a structure in which the surface gold crystals have no less than 30% planes with (1, 1, 1) orientation.

19. (New) The method of claims 17, wherein the gold-plated body is obtained by adding a crystal growth enhancer to a gold plating solution, immersing an electrically conductive substrate therein, and passing an electric current through said electrically conductive substrate and said gold plating solution having the crystal growth enhancer added thereto.